

Title (en)
COPPER ALLOY MATERIAL, AND METHOD FOR PRODUCTION THEREOF

Title (de)
KUPFERLEGIERUNGSMATERIAL UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
MATÉRIAU D'ALLIAGE DU CUIVRE ET SON PROCÉDÉ DE FABRICATION

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Application
EP 08739314 A 20080328

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Abstract (en)
[origin: EP2157199A1] A copper alloy material according to the present invention is characterized in that the copper alloy material includes: an element X between 0.1% and 4% by mass, in which the element X represents one transition element or not less than two elements selected from Ni, Fe, Co and Cr; an element Y between 0.01% and 3% by mass, in which the element Y represents one element or not less than two elements selected from Ti, Si, Zr and Hf; and a remaining portion to be comprised of copper and an unavoidable impurity, wherein the copper alloy material has an electrical conductivity of not less than 50% IACS, an yield strength of not less than 600 MPa, and a stress relaxation rate of not higher than 20% as to be measured after the same is maintained for 1000 hours at a state under applying a stress of 80% of the yield strength.

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Citation (search report)
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• See references of WO 2008123455A1

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